



Product Change Notification / RMES-04YPFT929

Date:

11-May-2023

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6248 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected PIC18F27Q8x, PIC18F47Q8x, PIC18F16xQ4x, PIC18F26Qxx and PIC18F46Q71 device families available in 20L (.300in) & 40L (.600in) PDIP and 28L (.300in) SPDIP packages assembled at MMT assembly site.

Affected CPNs:

[RMES-04YPFT929_Affected_CPN_05112023.pdf](#)
[RMES-04YPFT929_Affected_CPN_05112023.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected PIC18F27Q8x, PIC18F47Q8x, PIC18F16xQ4x, PIC18F26Qxx and PIC18F46Q71 device families available in 20L (.300in) & 40L (.600in) PDIP and 28L (.300in) SPDIP packages assembled at MMT assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (Branch) / (MMT)	Microchip Technology Thailand (Branch) / (MMT)
Wire Material	Au	CuPdAu
Die Attach Material	CRM-1064L	CRM-1064L
Molding Compound Material	GE800	GE800
Lead-Frame Material	CDA194	CDA194

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:In Progress

Estimated First Ship Date:May 30,2023 (date code: 2322)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	May 2023				
Workweek	1 8	1 9	2 0	2 1	2 2
Qual Report Availability		X			
Final PCN Issue Date		X			
Estimated Implementation Date					X

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:May 11, 2023: Issued final notification. Attached is the Qualification Report. Provided

estimated first ship date to be on May 30, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[**PCN_RMES-04YPFT929_Qual Report.pdf**](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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